



**AMES
GOLDSMITH**
Corp.

DEVELOPMENT PRODUCT

Copper Powder Type C1-2000

GENERAL DESCRIPTION

High density mono-dispersed 2 micron Cu powder.
Excellent oxidation resistance

APPLICATIONS

Thick film paste systems for BME MLCC inner electrodes and terminations, and other conductive polymer systems.

TYPICAL PROPERTIES

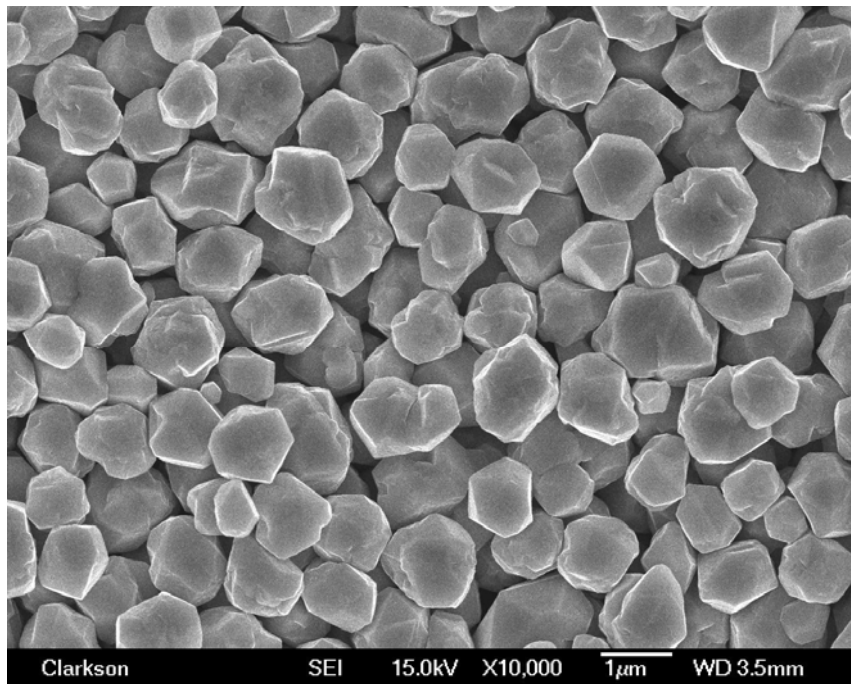
Physical Data:

Tap Density:	3.5-5.0 g/cm ³
Surface Area:	0.3-0.8 m ² /g
Loss on Drying: (1 hour @ 110°C in air)	<0.1 %

Particle Size Distribution:

D10	1.0 μm
D50	2.0 μm
D90	4.0 μm

PSD determined by Microtrac



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